

To all our customers

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Renesas Technology Corp.
Customer Support Dept.
April 1, 2003

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Keep safety first in your circuit designs!

1. Renesas Technology Corporation puts the maximum effort into making semiconductor products better and more reliable, but there is always the possibility that trouble may occur with them. Trouble with semiconductors may lead to personal injury, fire or property damage.

Remember to give due consideration to safety when making your circuit designs, with appropriate measures such as (i) placement of substitutive, auxiliary circuits, (ii) use of nonflammable material or (iii) prevention against any malfunction or mishap.

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1SS106

Silicon Schottky Barrier Diode for Various Detector,
High Speed Switching

RENESAS

ADE-208-153A (Z)

Rev. 1
Oct. 1998

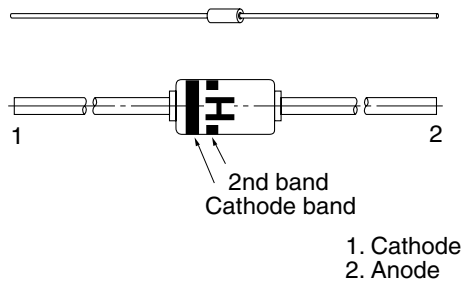
Features

- Detection efficiency is very good.
- Small temperature coefficient.
- High reliability with glass seal.

Ordering Information

Type No.	Cathode	2nd band	Mark	Package Code
1SS106	White	White	H	DO-35

Pin Arrangement



Absolute Maximum Ratings

(Ta = 25°C)

Item	Symbol	Value	Unit
Reverse voltage	V_R	10	V
Average rectified current	I_o	30	mA
Junction temperature	Tj	125	°C
Storage temperature	Tstg	-55 to +125	°C

Electrical Characteristics

(Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test Condition
Forward current	I_F	4.5	—	—	mA	$V_F = 1V$
Reverse current	I_R	—	—	70	μA	$V_R = 6V$
Capacitance	C	—	—	1.5	pF	$V_R = 1V$, f = 1MHz
Rectifier efficiency	η	70	—	—	%	$V_{in} = 2V_{rms}$, f = 40MHz, $R_L = 5k\Omega$, $C_L = 20pF$
ESD-Capability ^{*1}	—	100	—	—	V	C = 200pF, Both forward and reverse direction 1 pulse.

Notes: 1. Failure criterion; $I_R \geq 140\mu A$ at $V_R = 6V$

Main Characteristic

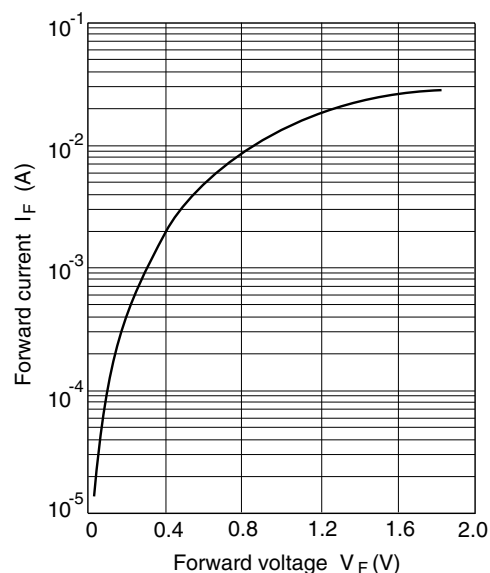


Fig.1 Forward current Vs. Forward voltage

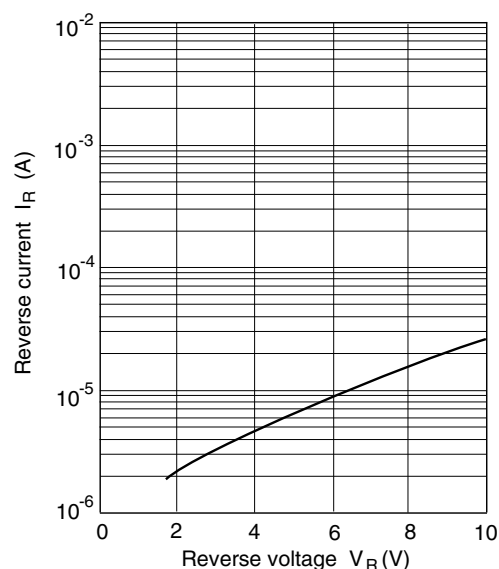


Fig.2 Reverse current Vs. Reverse voltage

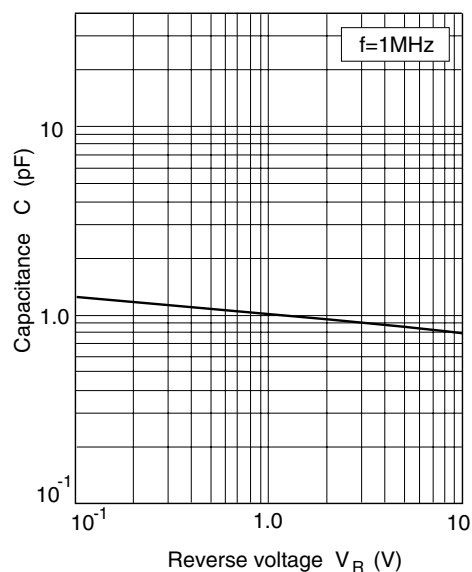
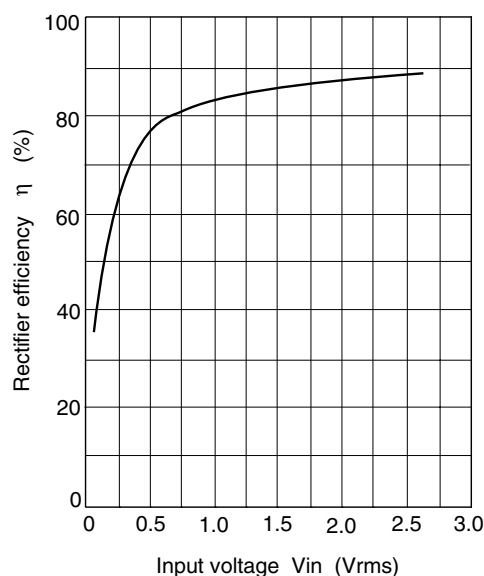
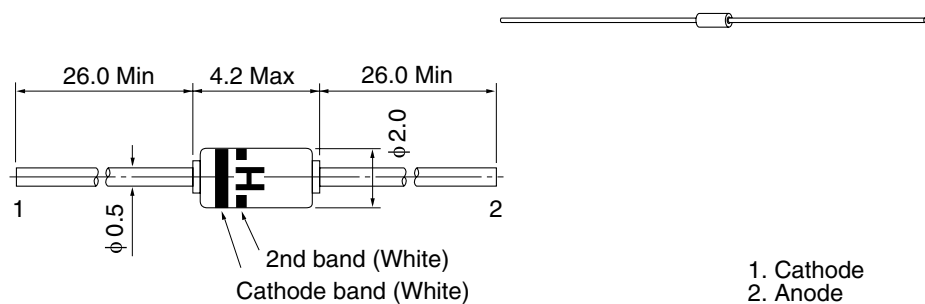


Fig.3 Capacitance Vs. Reverse voltage

Fig.4 Rectifier efficiency Vs. Input voltage V_{in}

Package Dimensions



Hitachi Code	DO-35
JEDECCode	DO-35
EIAJCode	SC-48
Weight(g)	0.13

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